

# BAP51-03

Silicon PIN diode

Rev. 5.1 — 8 February 2019

Product data sheet

## 1 Product profile

### 1.1 General description

General-purpose pin diode in an SOD323 small plastic SMD package.

### 1.2 Features and benefits



- Low diode capacitance: maximum 1.05 pF
- Low diode forward resistance: max. 0.7  $\Omega$
- AEC-Q101 qualified

### 1.3 Applications

- General RF applications

## 2 Pinning information

Table 1. Discrete pinning

Pin	Description	Simplified outline	Graphic symbol
1	cathode	 Top view	 sym006
2	anode		

## 3 Ordering information

Table 2. Ordering information

Type number	Package		Version
	Name	Description	
BAP51-03	-	plastic surface-mounted package; 2 leads	SOD323

## 4 Marking

Table 3. Marking code

Type number	Marking code
BAP51-03	A5 <sup>[1]</sup>

[1] The marking bar indicates the cathode (see simplified outline graphic in [Table 1](#)).



## 5 Limiting values

**Table 4. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
$V_R$	continuous reverse voltage		-	50	V
$I_F$	continuous forward current		-	50	mA
$P_{tot}$	total power dissipation	$T_{sp} \leq 90\text{ °C}$	-	500	mW
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		-65	+150	°C

## 6 Thermal characteristics

**Table 5. Thermal characteristics**

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		120	K/W

## 7 Characteristics

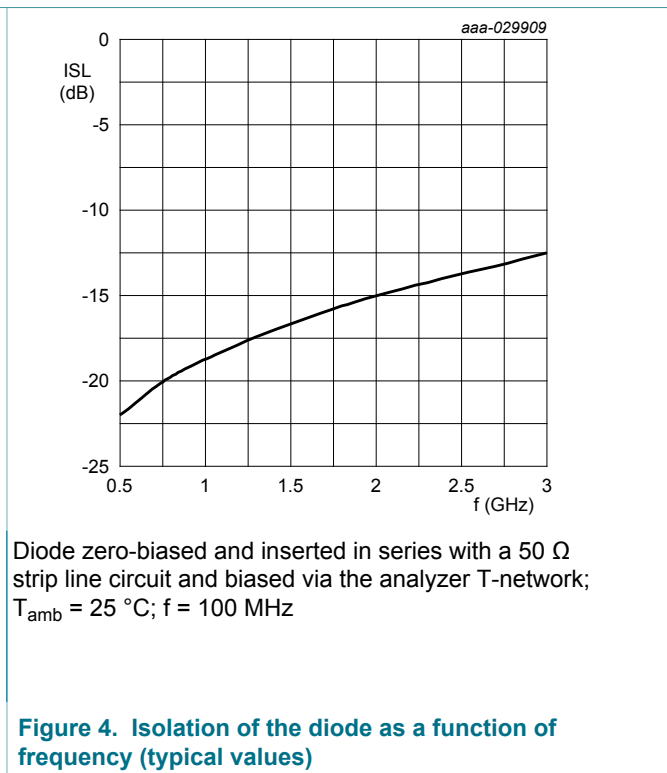
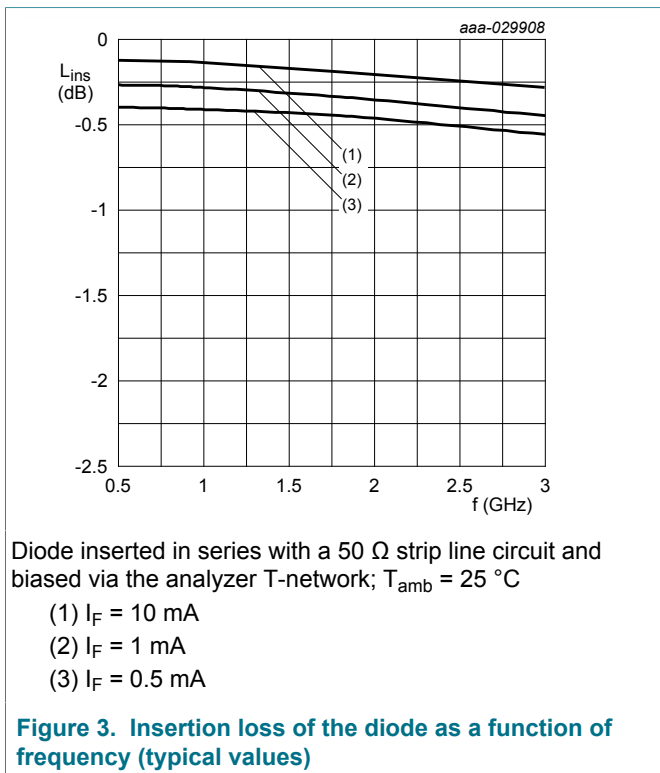
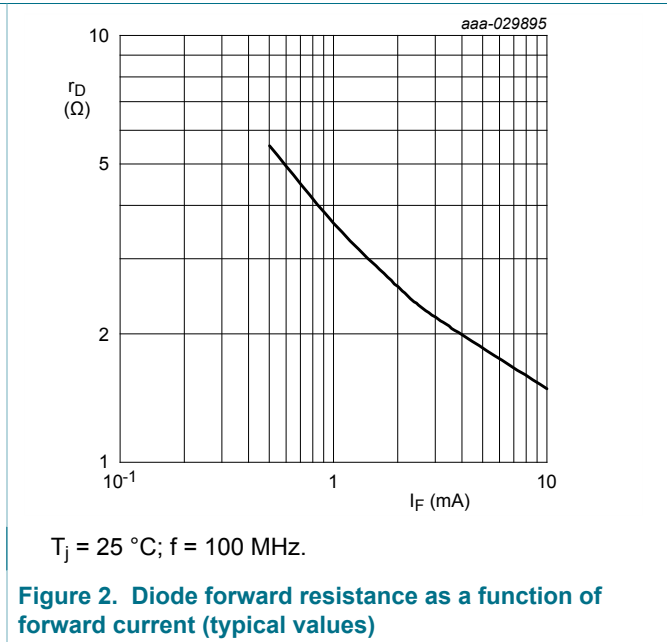
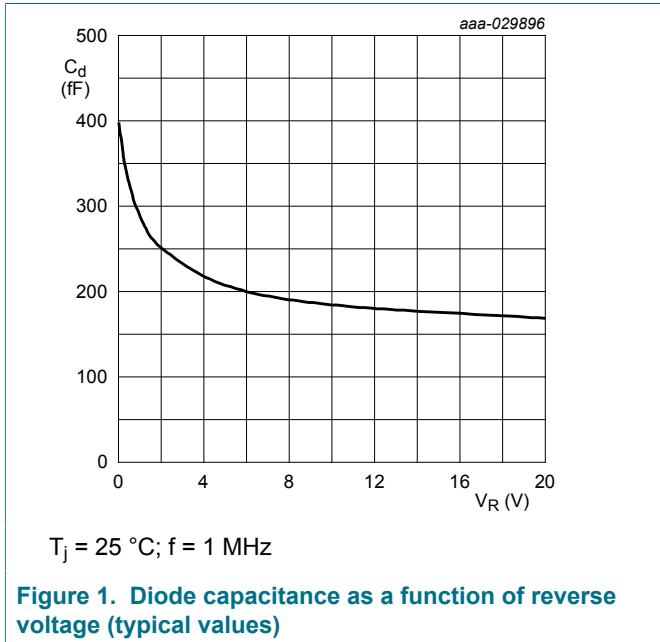
**Table 6. Characteristics**

$T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified.

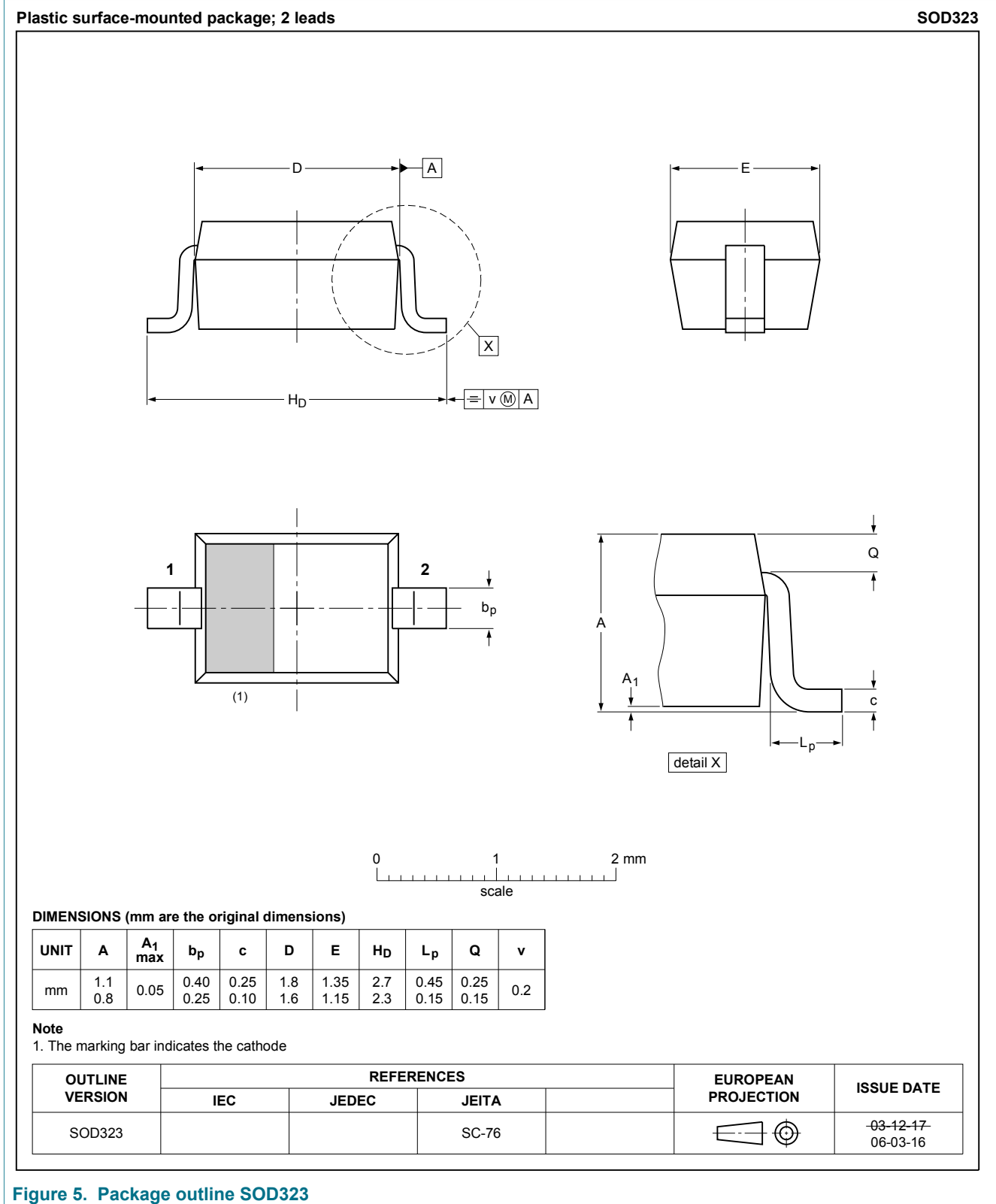
Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$V_F$	forward voltage	$I_F = 50\text{ mA}$	-	0.95	1.1	V	
$V_R$	reverse voltage	$I_R = 10\text{ }\mu\text{A}$	50	-	-	V	
$I_R$	reverse current	$V_R = 50\text{ V}$	-	-	100	nA	
$C_d$	diode capacitance	f = 1 MHz (see <a href="#">Figure 1</a> )					
		$V_R = 0\text{ V}$	-	0.4	-	pF	
		$V_R = 1\text{ V}$	-	0.3	0.55	pF	
		$V_R = 5\text{ V}$	-	0.2	0.35	pF	
$r_D$	diode forward resistance	f = 100 MHz (see <a href="#">Figure 2</a> )					
		$I_F = 0.5\text{ mA}$	[1]	-	5.5	9	$\Omega$
		$I_F = 1\text{ mA}$	[1]	-	3.6	6.5	$\Omega$
		$I_F = 10\text{ mA}$	[1]	-	1.5	2.5	$\Omega$
$\tau_L$	charge carrier life time	when switched from $I_F = 10\text{ mA}$ to $I_R = 6\text{ mA}$ ; $R_L = 100\text{ }\Omega$ ; measured at $I_R = 3\text{ mA}$	-	550	-	ns	

[1] Guaranteed on AQL basis; inspection level S4, AQL 1.0

**8 Graphical data**



**9 Package outline**



**Figure 5. Package outline SOD323**

## 10 Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP51-03 v.5.1	20190208	Product data sheet	-	BAP51-03 v.5
Modifications:	• aligned the title of the data sheet with the description on the Internet			
BAP51-03 v.5	20181126	Product data sheet	-	BAP51-03 v.3.1
Modifications:	• AEC-Q101 qualification added to the features and benefits • <a href="#">Section 1.2</a> "Features and benefits" has been updated. • The "Legal information" pages have been updated to automotive version			
BAP51-03 v.4.1	20040211	Product data sheet	-	-

## 11 Legal information

### 11.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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